

ABSTRACT

The present invention provides a solder deposition method that includes the step of forming a dam around an electrode on a substrate, the step of applying a solder precipitating composition to the substrate, and the step of depositing solder on the surface of the electrode while heating the solder precipitating composition applied. This solder deposition method is suitable for forming large bumps at fine pitches. In particular, it is capable of depositing solder in a desired height precisely and easily, and yet preventing occurrence of voids.